

SCH300 Series OCXOs

Software Compensated, Ultra-High Stability, Surface Mount

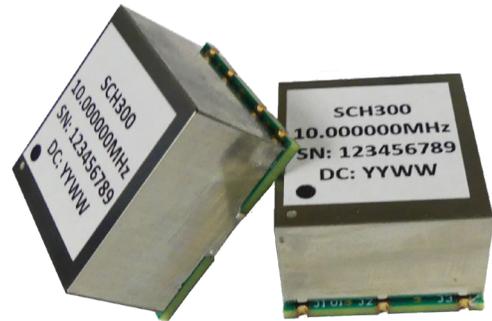
Key Features

- Standard Frequencies:
10, 12.8, 20, 25, and 100 MHz
- SMT package (22 mm x 25.4 mm)
- Temperature stability options up to +/- 0.25 ppb
- 3.3V or 5.0V supply options
- CMOS or Sine Output
- RoHS Compliant / Lead Free



Common Applications

- SATCOM terminals
- Cellular base stations
- Test Instrumentation
- Microwave Communications
- Military communication systems



Functional Description

The SCH300 highly stable product family utilizes Esterline Research and Design's patented MSAC compensation architecture to improve performance over the entire operating temperature range.

Traditionally, this level of stability over temperature has only been available in double-oven oscillators. Harnessing the power of our MSAC technology, the SCH300 series OCXO is able to achieve these ultra-high levels of stability in a single-oven design. Naturally, this results in a significantly smaller footprint, ideal for higher-level designs where space is at a premium. Additionally, the absence of a second oven provides a notable savings in power consumption.

This design allows the user to choose frequency stabilities as precise as ± 0.25 ppb over the operating temperature range.

Absolute Maximum Ratings:

| Parameter | Minimum | Typical | Maximum | Units |
|-------------------------------|---------|---------|---------|-------|
| Storage Temperature | -55 | - | 105 | °C |
| Supply Voltage (Vcc) | -0.5 | - | 5.5 | Vdc |
| Operating Supply Voltage 3.3V | 3.135 | 3.30 | 3.465 | Vdc |
| Operating Supply Voltage 5.0V | 4.75 | 5.0 | 5.25 | Vdc |

Absolute Ratings: Exceeding values beyond those listed in the table above may cause permanent damage to the device. Exposure to conditions outside of those listed in the "Standard Specifications" table may adversely impact device reliability and result in failures not covered by warranty.

Standard Specifications:

| Parameter | Minimum | Typical | Maximum | Units | Notes |
|--|-----------------------------------|----------|----------|---------|--|
| Frequency Range | 10.0, 12.8, 20.0, 25.0, or 100MHz | | | MHz | Other frequencies may be available upon request |
| Operational Temperature Range | | | | | See ordering options. |
| Frequency vs. Temperature ⁴ | | | | | See ordering options. |
| Calibration Tolerance | -200 | | +200 | ppb | At time of shipment. |
| Frequency vs. Supply | -0.2 | | +0.2 | ppb | 1% Change |
| Frequency vs Load | -0.2 | | +0.2 | ppb | 1% Change |
| Startup Time | | | 500 | ms | To reach 90% of final amplitude and ± 200 ppb of 30-minute frequency |
| Warmup Time | | | 5 | Minutes | Within ± 100 ppb of 60-minute frequency at 25°C |
| Aging ^{2, 3} | | | | | See ordering options |
| Supply Voltage ⁵ | | | | Volts | |
| Option 01 | 3.135 | 3.3 | 3.465 | Volts | "Typical" column refers to nominal. |
| Option 02 | 4.75 | 5.00 | 5.25 | Volts | "Typical" column refers to nominal. |
| Power Consumption | | | | | |
| 3.3V Steady State at 25°C | | | 1.5 | Watts | Measured in still air. |
| 3.3V Turn-on Power | | | 3.6 | Watts | Measured in still air. |
| 5.0V Steady State at 25°C | | | 2.5 | Watts | Measured in still air. |
| 5.0V Turn-on Power | | | 4.2 | Watts | Measured in still air. |
| Phase Jitter (BW: 10Hz to Fo/2) | | | 1.0 | ps rms | |
| Allan Deviation | | 2.0 E-12 | 1.0 E-11 | | Tau = 10s F = 10 MHz |

Output Characteristics:

| Parameter | Minimum | Typical | Maximum | Units | Notes |
|--------------------------------|---------|---------|---------|-------|------------------------------|
| CMOS Output Option | | | | | Load = 15 pF |
| Output Voltage High (Voh) | 3.0 | | | Volts | |
| Output Voltage Low (Vol) | | | 0.4 | Volts | |
| Output Current High (Ioh) | -0.4 | | | mA | |
| Output Current Low (Iol) | | | 0.4 | mA | |
| Duty Cycle | 45 | 50 | 55 | % | |
| Rise/Fall Time | | | 6 | ns | Measured between 10% and 90% |
| Sine Wave Output Option | | | | | Load = 50 Ω |
| Output Power | 5 | 7 | 9 | dBm | |
| Harmonics | | | -40 | dBc | |
| Spurious | | | -70 | dBc | |

Phase Noise Characteristics:

| Parameter | Minimum | Typical | Maximum | Units |
|----------------|---------|---------|---------|--------|
| 1 Hz Offset | | | -85 | dBc/Hz |
| 10 Hz Offset | | | -115 | dBc/Hz |
| 100 Hz Offset | | | -140 | dBc/Hz |
| 1 KHz Offset | | | -145 | dBc/Hz |
| 10 KHz Offset | | | -150 | dBc/Hz |
| 100 KHz Offset | | | -150 | dBc/Hz |

Restabilization Time:⁶

| Off Time | Restabilization Time |
|-------------|-------------------------|
| < 1 Hour | < 2 Hours |
| < 6 Hours | < 12 Hours |
| < 24 Hours | < 48 Hours |
| 1 - 16 Days | 48 Hours + 1/4 Off Time |
| > 16 Days | < 6 Days |

Environmental Characteristics:

| Environmental Phenomenon | Response |
|--------------------------|---|
| Shock | 500 G's 1ms, Half sine, 2 shocks per direction, per MIL-STD 202G, Method 213B, Test Condition D |
| Sinusoidal Vibration | 0.06" Displacement Amplitude or 10G's peak, 10 to 500 Hz, per MIL-STD-202G, Method 204D, Test Condition A |
| Random Vibration | 5.35 G's RMS, 20 – 2000 Hz per MIL-STD-202G, Method 214, Test Condition 1A, 15 minutes per axis. |
| Moisture | 10 Cycles, 95% RH, per MIL-STD-202G, Method 112 |
| Marking Permanency | Per customer requirements. |

Manufacturing Processes:

| Process | Instructions |
|----------------------|--|
| Solder Process | RoHS-compliant, lead-free. See figure 1. |
| In-Line reflow | Refer to recommended reflow pre-heat and reflow temperatures in figure 1. Package material consists of metal cover with FR4 substrate. Component solder is lead-free high temperature eutectic alloy with melting point of 221°C |
| In-Line Oven profile | We recommend using KIC profiler or similar device placing one of the thermocouples on the device to ensure that the internal package temperature does not exceed 221°C |
| Removal of Device: | If for any reason the device needs to be removed from the board, use a temperature-controlled repair station with profile monitoring capabilities. Following a monitored profile will ensure the device is properly heated prior to reflow. |
| Cleaning Process | Device is non-hermetic, water resistant with weep holes in each corner that allow moisture to be removed during the drying cycle. We recommend in-line warm-water wash with air knife and drying capabilities. If cleaner does not have drying capabilities, then use hot-air-circulated oven. Boards should be placed vertically in the oven for good water runoff. <i>Device must be dried properly prior to use! Do not submerge the device!</i> |
| Saponifier | If saponifier is used, make sure the device is rinsed properly to ensure all residues are removed. pH of saponifier should not exceed 10. |
| Drying Temperature | Between 85 and 100 °C |
| Drying Time | Varies depending on final assembly size and thermal mass. |

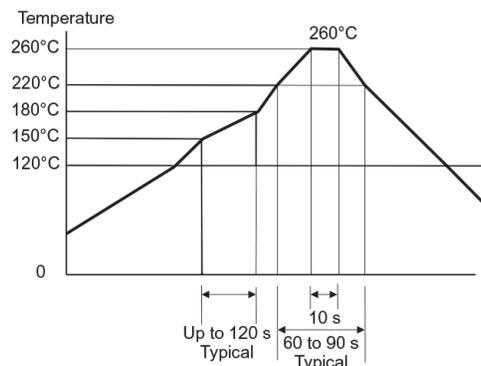
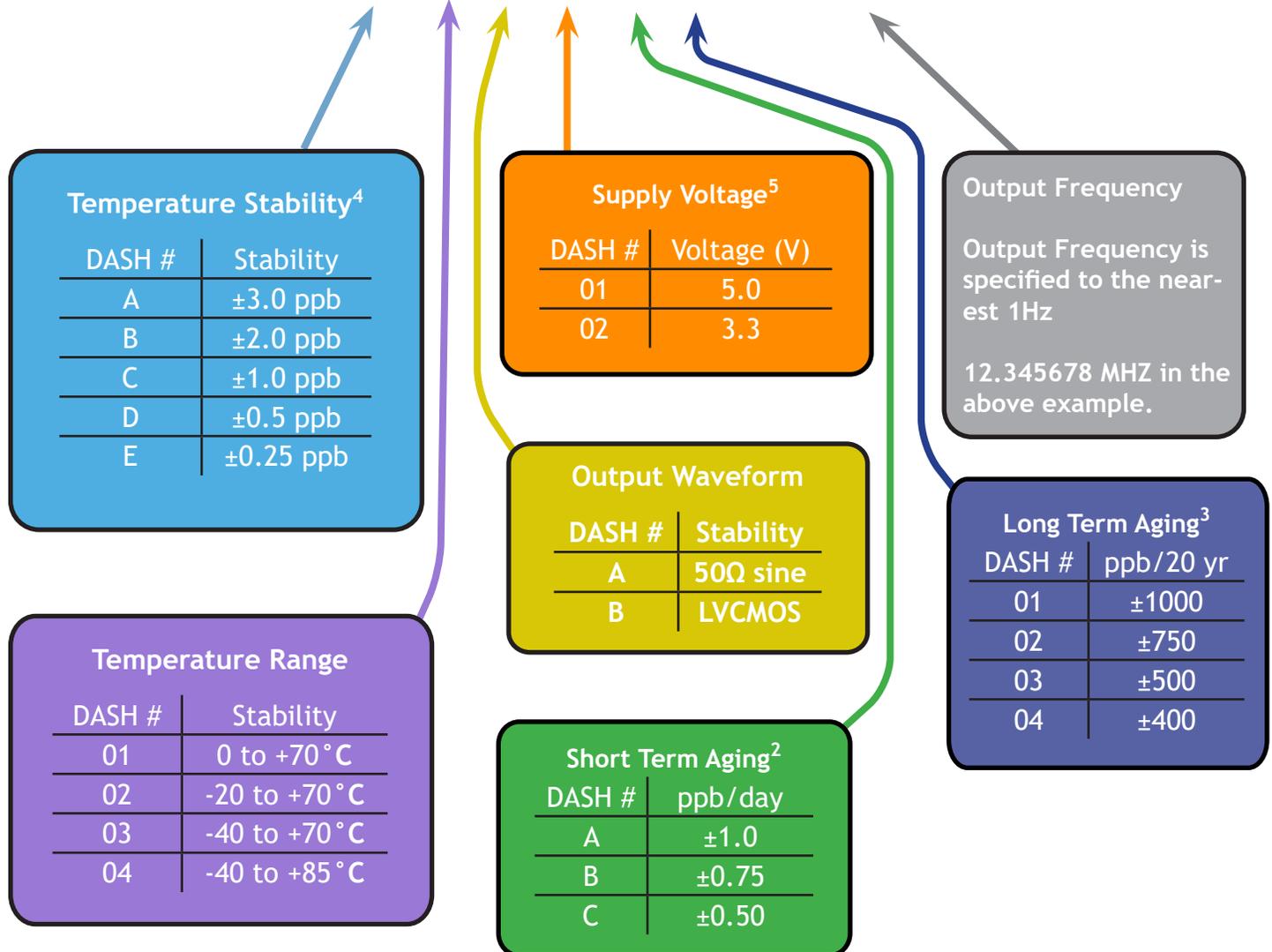


Figure 1: Solder Profile (Meets IPC/JEDEC J-STD-020C)

Ordering Information:¹

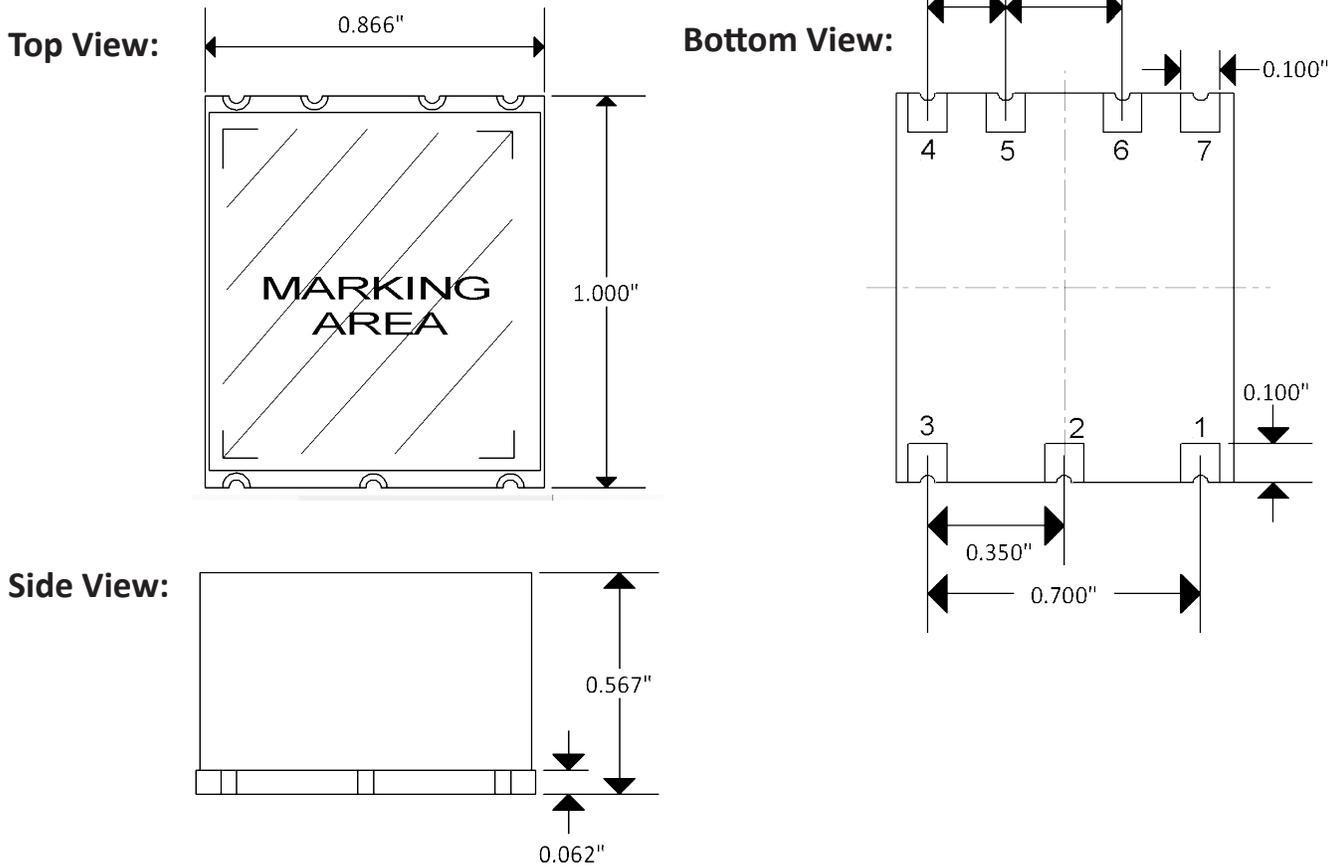
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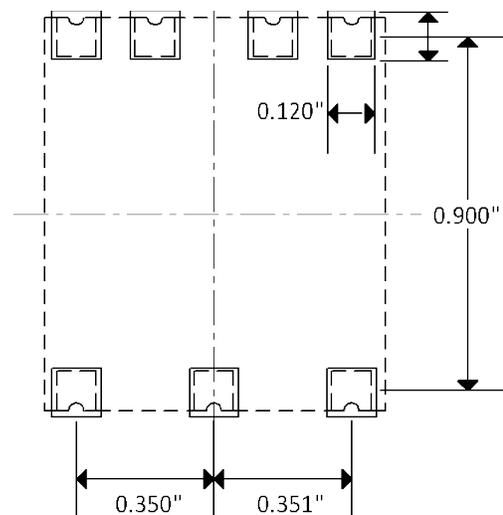
Notes:

- 1.) Not all combinations of options are available. Consult factory for additional guidance.
- 2.) Daily rate is measured after 48 hours of continuous operation.
- 3.) Long-term aging include temperature performance, supply voltage change, and load change.
- 4.) Temperature stability is based on $(F_{\max} - F_{\min})/2$
- 5.) Supply voltage must reach V_{CC} levels monotonically with a ramp-up time of < 12ms.
- 6.) For a given off time, the time required to meet daily aging and ADEV requirements.

Mechanical Specifications:



Recommended Pad Layout



For best signal integrity, do not run traces beneath the part, and ensure the area under the board is ground plane.